

N-Channel Super Junction Power MOSFET IV

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

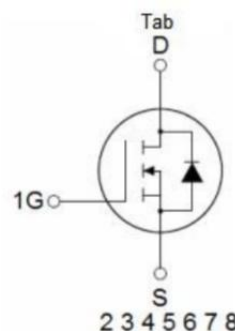
Features

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

$V_{DS\ min@T_{jmax}}$	710	V
$R_{DS(ON)TYP}$	165	mΩ
I_D	18	A
Q_g	30	nC

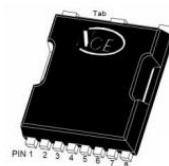


Schematic diagram

✧ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65NF190LL	TOLL-8L	NCE65NF190LL



TOLL-8L

Table 1. Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	650	V
Gate-Source Voltage ($V_{DS}=0V$) AC ($f>1\text{ Hz}$)	V_{GS}	± 30	V
Gate-Source Voltage ($V_{DS}=0V$) DC	V_{GS}	± 20	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	18	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	12.6	A
Pulsed drain current (Note 1)	$I_{DM(pluse)}$	54	A
Maximum Power Dissipation($T_c=25^\circ\text{C}$)	P_D	194	W
Derate above 25°C		1.29	W/ $^\circ\text{C}$
Avalanche current(Note 1)	I_{AS}	4	A
Drain Source voltage slope, $V_{DS} \leq 480\text{ V}$,	dv/dt	50	V/ns
Reverse diode dv/dt , $V_{DS} \leq 480\text{ V}, I_{SD} < I_D$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	$-55...+175$	$^\circ\text{C}$

* limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	0.77	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	62	$^{\circ}\text{C}/\text{W}$

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			300	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	3.5	4.2	5.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =9A		165	190	mΩ
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		1550	1950	pF
Output Capacitance	C _{oss}			60		pF
Reverse Transfer Capacitance	C _{rss}			5		pF
Total Gate Charge	Q _g	V _{DS} =480V,I _D =9A, V _{GS} =10V		30		nC
Gate-Source Charge	Q _{gs}			12.5		nC
Gate-Drain Charge	Q _{gd}			11		nC
Gate plateau voltage	V _{gp}			7.5		V
Intrinsic gate resistance	R _G	f = 1 MHz open drain		1.5		Ω
Switching times						
Turn-on Delay Time	t _{d(on)}	V _{DD} =380V,I _D =9A, R _G =1.7Ω,V _{GS} =10V		43		nS
Turn-on Rise Time	t _r			17		nS
Turn-Off Delay Time	t _{d(off)}			94		nS
Turn-Off Fall Time	t _f			26		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T _C =25℃			18	A
Pulsed Source-drain current(Body Diode)	I _{SDM}				54	A
Forward On Voltage	V _{SD}	T _j =25℃,I _{SD} =18A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}	T _j =25℃,I _F =9A, di/dt=100A/μs		125		nS
Reverse Recovery Charge	Q _{rr}			0.51		uC
Peak Reverse Recovery Current	I _{rrm}			8.2		A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_j=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

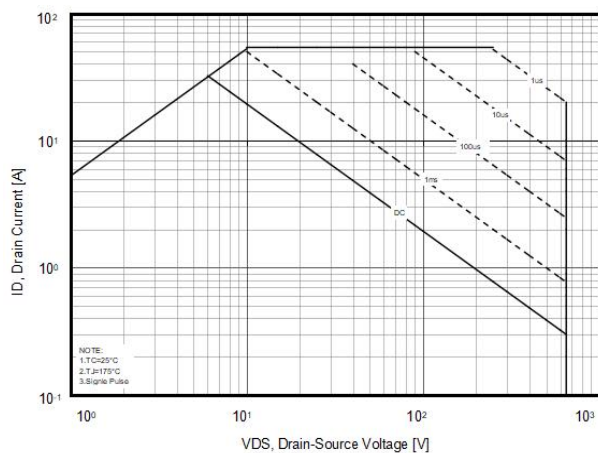


Figure2. Capacitance

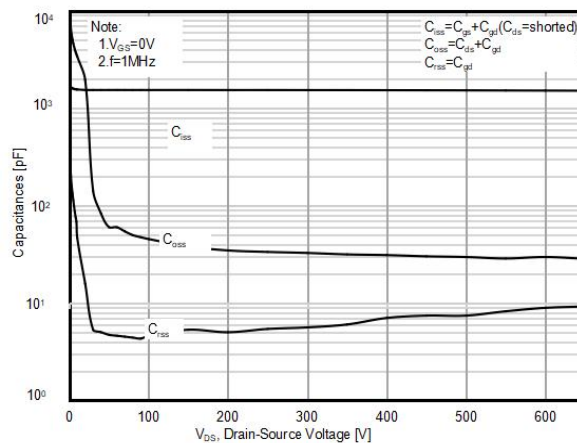


Figure3. Transfer characteristics

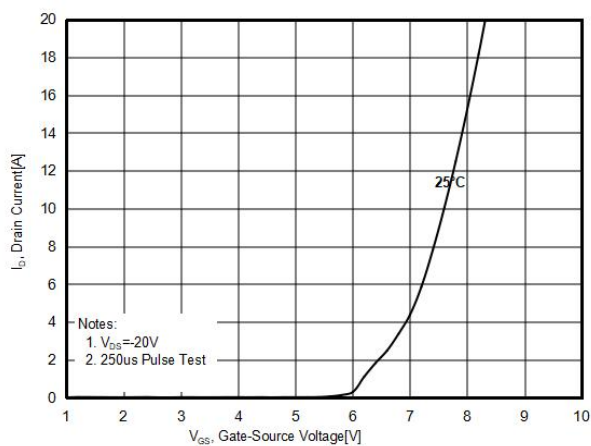


Figure4. Output characteristics

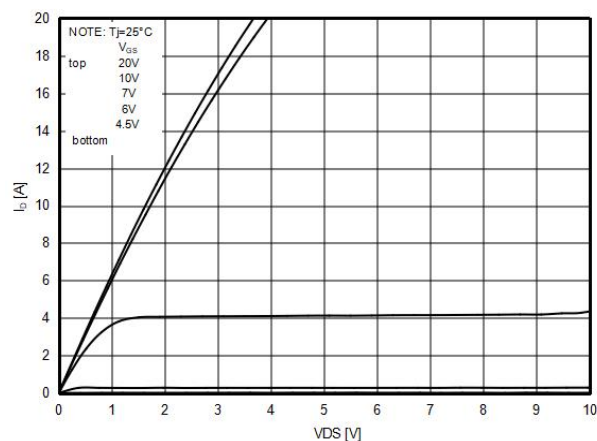


Figure5. $R_{DS(ON)}$ vs Junction Temperature

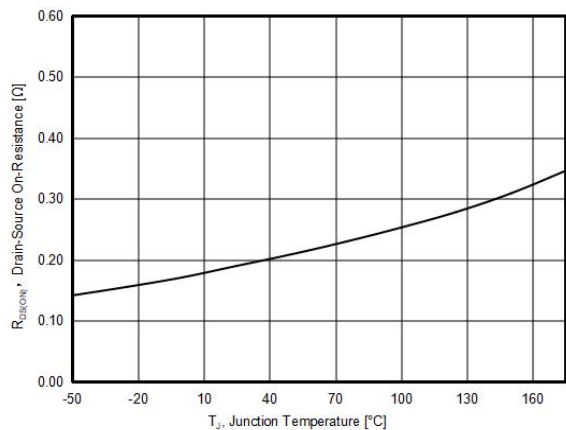


Figure6. BV_{DSS} vs Junction Temperature

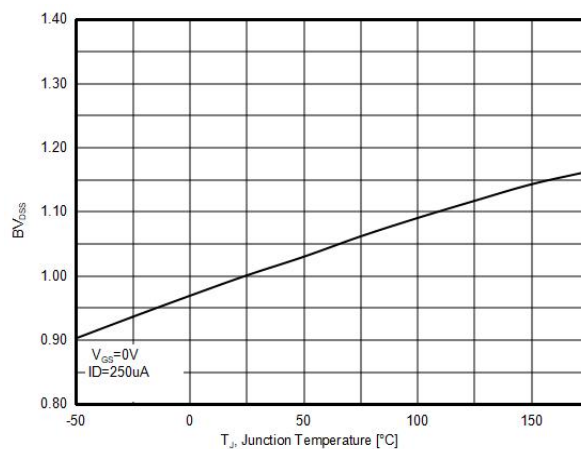


Figure7. Maximum I_D vs Junction Temperature

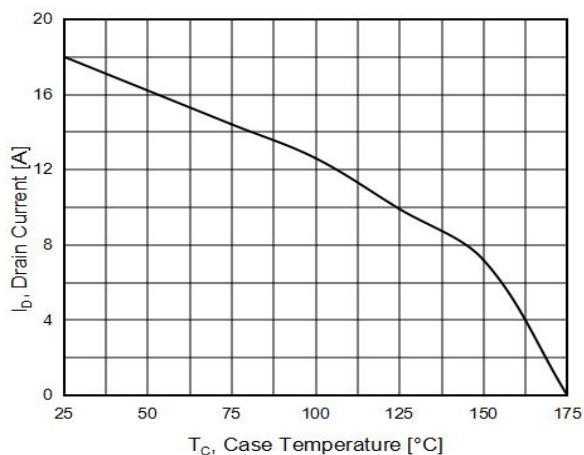


Figure8. Gate charge waveforms

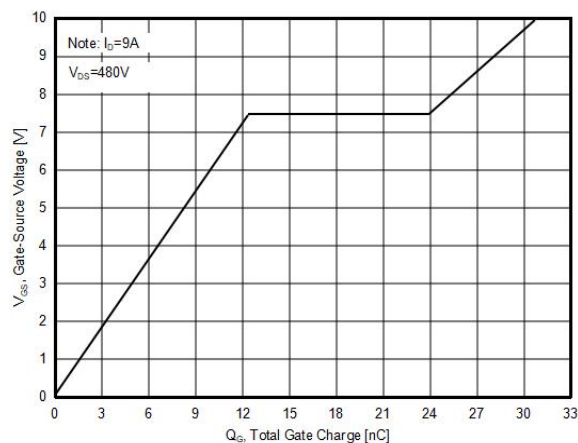


Figure9. Static drain-source on resistance

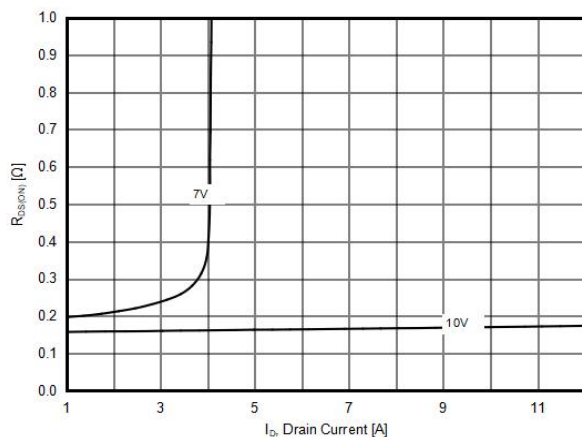
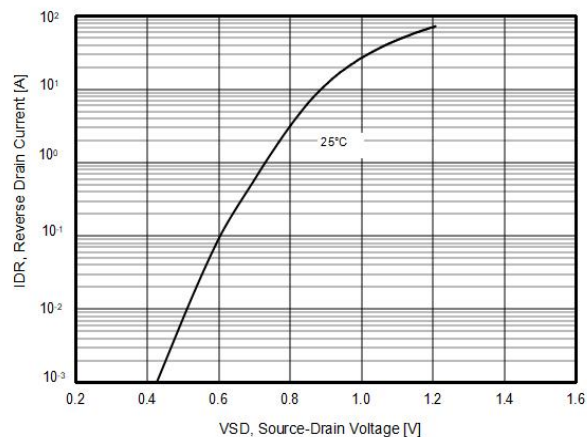
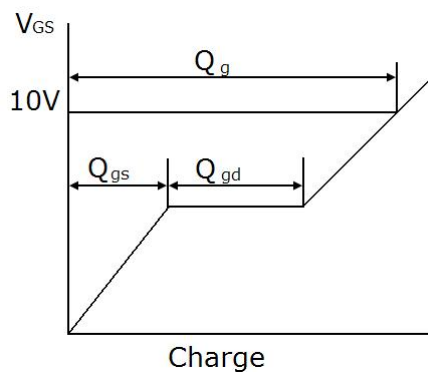
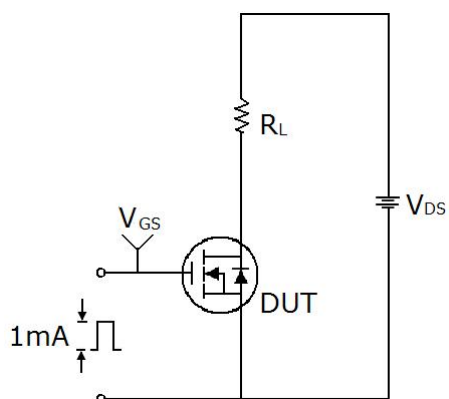


Figure10. Source-Drain Diode Forward Voltage

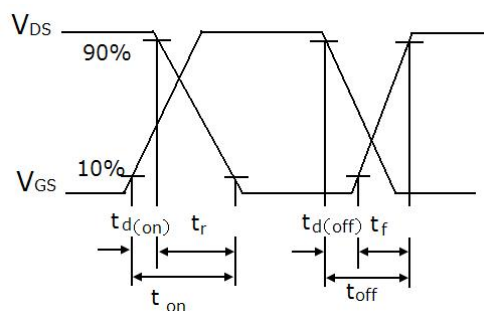
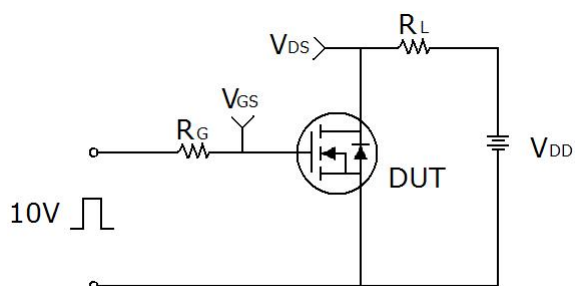


Test circuit

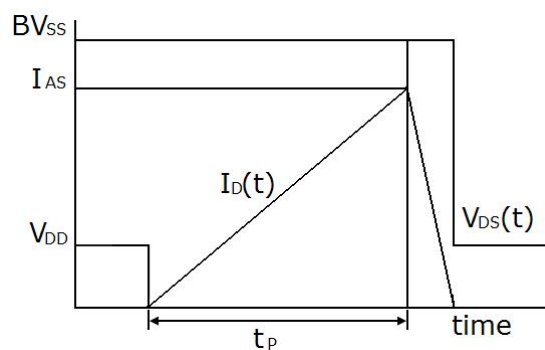
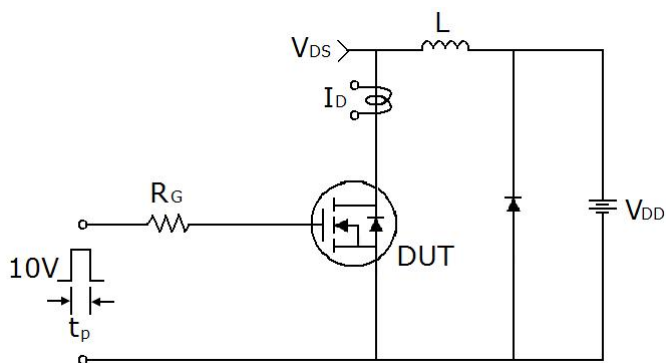
1) Gate charge test circuit & Waveform



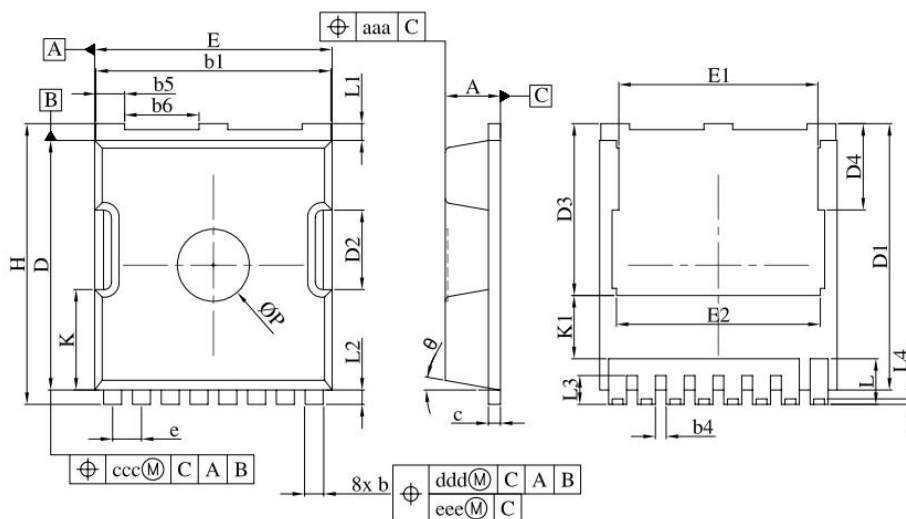
2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms



TOLL-8L Package Information



SYMBOL	Dimensions In Millimeters			Dimensions In Inches		
	Min	Typ	Max	Min	Typ	Max
A	2.20	2.30	2.40	0.087	0.091	0.094
b	0.70	0.80	0.90	0.028	0.031	0.035
b1	9.70	9.80	9.90	0.382	0.386	0.390
b4	0.30	0.40	0.50	0.012	0.016	0.020
b5	1.10	1.20	1.30	0.043	0.047	0.051
b6	3.00	3.10	3.20	0.118	0.122	0.126
c	0.40	0.50	0.60	0.016	0.020	0.024
D	10.28	10.38	10.55	0.405	0.409	0.415
D1	10.98	11.08	11.18	0.432	0.436	0.440
D2	3.20	3.30	3.40	0.126	0.130	0.134
D3	7.00	7.15	7.30	0.276	0.281	0.287
D4	3.44	3.59	3.74	0.135	0.141	0.147
e	1.10	1.20	1.30	0.043	0.047	0.051
E	9.80	9.90	10.00	0.386	0.390	0.394
E1	8.20	8.30	8.40	0.323	0.327	0.331
E2	8.35	8.50	8.65	0.329	0.335	0.341
H	11.50	11.68	11.85	0.453	0.460	0.467
K	4.08	4.18	4.28	0.161	0.165	0.169
K1	2.45	--	--	0.096	--	--
L	1.60	1.90	2.10	0.063	0.075	0.083
L1	0.50	0.70	0.90	0.020	0.028	0.035
L2	0.50	0.60	0.70	0.020	0.024	0.028
L3	1.00	1.20	1.30	0.039	0.047	0.051
L4	0.13	0.23	0.33	0.005	0.009	0.013
P	2.85	3.00	3.15	0.112	0.118	0.124

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